

1 ABSTRACT OF THE DISCLOSURE

2 A semiconductor workpiece holder used in electroplating systems
3 for plating metal layers onto a semiconductor workpieces, and is of
4 particular advantage in connection with plating copper onto
5 semiconductor materials. The workpiece holder includes electrodes which
6 have a contact face which bears against the workpiece and conducts
7 current therebetween. The contact face is provided with a contact face
8 outer contacting surface which is made from a contact face material
9 similar similar to the workpiece plating material which is to be plated
10 onto the semiconductor workpiece. The contact face can be formed by
11 pre-conditioned an electrode contact using a plating metal which is
12 similar to the plating materials which is to be plated onto the
13 semiconductor workpiece.
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